L Number	Hits	Search Text	DB	Time stamp
1	7	((polyetheramide) or (polyether adj amide)) with (mask$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/30 07:51
2	3039095	pit or dimple or cavity or cavities or recess or recesses or hole or depression	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/30 07:41
3	29	((polyetheramide) or (polyether adj amide)) same (pit or dimple or cavity or cavities or recess or recesses or hole or depression)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/30 07:44
4	92395	(pit or dimple or cavity or cavities or recess or recesses or hole or depression) with (adhesion or adher$4 or bond$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/30 07:45
5	34	((pit or dimple or cavity or cavities or recess or recesses or hole or depression) with (adhesion or adher$4 or bond$4)) and 216/34-35.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/30 07:46
6	1	(((pit or dimple or cavity or cavities or recess or recesses or hole or depression) with (adhesion or adher$4 or bond$4)) and 216/34-35.ccls.) and 216/27	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/30 07:46
7	33	(((pit or dimple or cavity or cavities or recess or recesses or hole or depression) with (adhesion or adher$4 or bond$4)) and 216/34-35.ccls.) not (((((pit or dimple or cavity or cavities or recess or recesses or hole or depression) with (adhesion or adher$4 or bond$4)) and 216/34-35.ccls.) and 216/27)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/30 07:50
8	129	((polyetheramide) or (polyether adj amide)) with (bond$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/30 07:51
9	6	(((polyetheramide) or (polyether adj amide)) with (bond$4)) same (etch$4 or pattern$4 or remov$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/30 07:53
10	123	(((polyetheramide) or (polyether adj amide)) with (bond$4)) not ((((polyetheramide) or (polyether adj amide)) with (bond$4)) same (etch$4 or pattern$4 or remov$4))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/30 07:53

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